TITLE OF THE INVENTION

STACKED SEMICONDUCTOR DEVICE AND METHOD OF PRODUCING THE SAME

CROSS REFERENCE TO RELATED APPLICATION

This application is a division of Ser. No. 09/940,625, filed August 29, 2001, now Patent Number 6,621,169

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention generally relates to semiconductor devices and methods of producing the semiconductor devices, and, more particularly, to a stacked semiconductor device having a plurality of semiconductor chips stacked as one package and a method of producing such a stacked semiconductor device.

2. Description of the Related Art

In recent years, portable electronic devices such as mobile telephones and non-volatile memory media such as IC memory cards have been becoming smaller and smaller. Along with this trend, there have been demands for devices and memory media having a smaller number of components and a smaller size. Accordingly, it is desired to develop a technique of effectively packaging semiconductor chips that are main components constituting those electronic devices and memory media. Examples of such packages that satisfy the above demands include a chip scale package (CSP) that is almost as small as a semiconductor chip and a multi-chip package (MCP) that accommodates a plurality of semiconductor chips in one package.

The CSP or MCP is realized by stacking and turning a plurality of semiconductor chips into one package. This technique is represented by a stacked multi-chip package (S-MCP).

FIG. 1 shows the structure of a conventional S-MCP in which two semiconductor chips are stacked. As shown in FIG. 1, a semiconductor chip 2 is mounted on a substrate 4,